

WAFFLE PACK HANDLING INSTRUCTIONS

Opening

Step 1

Remove carrier clip. Do not allow separation between the waffle pack and cover.



Step 2

Place lidded waffle pack on a flat surface. Avoid separation between the waffle pack and cover.



Step 3

Gently tap the cover using your finger or a set of tweezers. This will remove any chips that are clinging to the inside cover or paper.



Step 4

Lift cover, making sure if there is no paper to look at the bottom side of the cover to ensure no chips remain stuck to it.



Step 5

Remove the layer(s) of paper if present. They should be slid off the waffle pack with light pressure.



Step 6

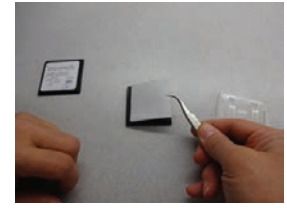
Remove the chips from the waffle. The use of vacuum tweezers is strongly suggested. Tweezers should not be used to remove chips.



Closing

Step 1

When closing the package, if there was paper in place make sure it is aligned properly.



Step 2

Place the lid on the waffle, making sure the cut corner on the lid is oriented to match the bottom.



Step 3

Avoiding separation between the waffle and cover, slide the carrier clip on.



Notes: Thermistors, by definition are not ESD Sensitive per MIL-DTL-39032E, Table 1.

QT05013-016 Application Note

Approved by: Dave Moe 10/22/12